Taiwan Semiconductor

2A, 200V- 1000V Fast Recovery Surface Mount Rectifiers

FEATURES

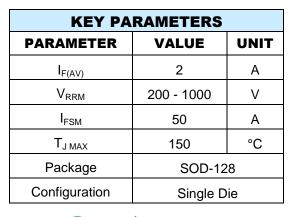
- Glass passivated junction chip
- Ideal for automated placement
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters, computer and telecommunication.

MECHANICAL DATA

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Pure tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.027 g (approximately)







SOD-128

| ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted) | | | | | | | | |
|---|------------------------------|---------------------|-------------|--------|--------|--------|--------|------|
| PARAMETER | | SYMBOL | RS2DFS | RS2GFS | RS2JFS | RS2KFS | RS2MFS | UNIT |
| Marking code on the device | | | RS2DFS | RS2GFS | RS2JFS | RS2KFS | RS2MFS | |
| Repetitive peak reverse voltage | | V _{RRM} | 200 | 400 | 600 | 800 | 1000 | V |
| Reverse voltage, total rms value | | V _{R(RMS)} | 140 | 280 | 420 | 560 | 700 | V |
| Forward current | | I _F | 2 | | | | | А |
| Surge peak forward current, single half sine- | 8.3ms at $T_A = 25^{\circ}C$ | | | | 50 | | | А |
| wave superimposed on rated load per diode | 1.0ms at $T_A = 25^{\circ}C$ | IFSM | 140 | | | | | А |
| Junction temperature | | TJ | -55 to +150 | | | | | °C |
| Storage temperature | | T _{STG} | -55 to +150 | | | | | °C |



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| THERMAL PERFORMANCE | | | | |
|--|------------------|-----|------|--|
| PARAMETER | SYMBOL | ТҮР | UNIT | |
| Junction-to-lead thermal resistance | R _{ejl} | 16 | °C/W | |
| Junction-to-ambient thermal resistance | R _{eja} | 73 | °C/W | |
| Junction-to-case thermal resistance | R _{eJC} | 14 | °C/W | |

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

| PARAMETER | | CONDITIONS | SYMBOL | ТҮР | MAX | UNIT |
|---|----------------------------|---|-----------------|------|------|------|
| | | I _F = 1.0A, T _J = 25°C | V _F | 0.93 | - | V |
| Forward voltage ⁽¹⁾ | RS2DFS | $I_F = 2.0A, T_J = 25^{\circ}C$ | | 1.01 | 1.30 | V |
| | RS2GFS RS2JFS | I _F = 1.0A, T _J = 125°C | | 0.78 | - | V |
| | | I _F = 2.0A, T _J = 125°C | | 0.88 | 1.02 | V |
| | | I _F = 1.0A, T _J = 25°C | | 0.98 | - | V |
| | RS2KFS | $I_F = 2.0A, T_J = 25^{\circ}C$ | | 1.06 | 1.30 | V |
| | RS2MFS | I _F = 1.0A, T _J = 125°C | | 0.83 | - | V |
| | | I _F = 2.0A, T _J = 125°C | | 0.93 | 1.05 | V |
| Reverse current @ rated V _R ⁽²⁾ | | $T_J = 25^{\circ}C$ | | - | 1 | μA |
| | | T _J = 125°C | I _R | - | 40 | μA |
| | RS2DFS RS2GFS | | t _{rr} | - | 150 | ns |
| Reverse recovery time | RS2JFS | I _F =0.5A,I _R =1.0A, Irr=0.25A | | - | 250 | ns |
| | RS2KFS RS2MFS | | | - | 500 | ns |
| Junction capacitance | RS2DFS RS2GFS RS2JFS | 1 MHz, V _R =4.0V | CJ | 11 | - | pF |
| · | RS2KFS RS2MFS | | | 10 | - | pF |

Notes:

(1) Pulse test with PW=0.3 ms

(2) Pulse test with PW=30 ms

| ORDERING INFORMATION | | | |
|------------------------------|---------|-------------------|--|
| ORDERING CODE ⁽¹⁾ | PACKAGE | PACKING | |
| RS2xFS M3G | SOD-128 | 3,500 / 7" reel | |
| RS2xFS M2G | SOD-128 | 14,000 / 13" reel | |

Notes:

(1) "x" defines voltage from 200V(RS2DFS) to 1000V(RS2MFS)



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

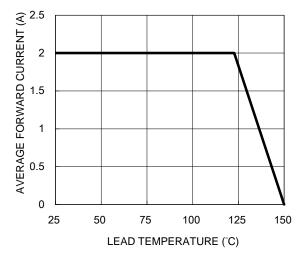


Fig.3 Typical Reverse Characteristics

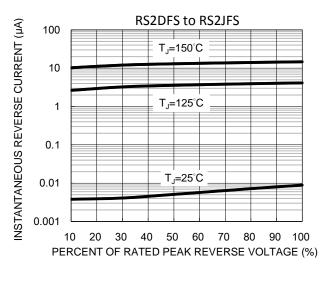
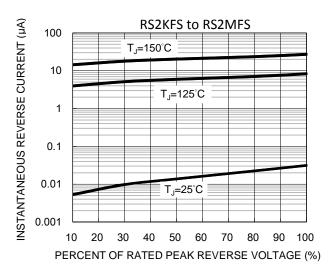


Fig.5 Typical Reverse Characteristics



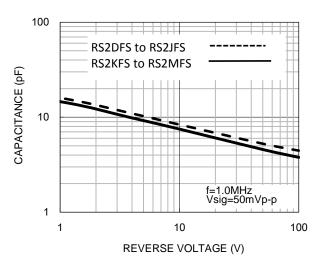


Fig.2 Typical Junction Capacitance



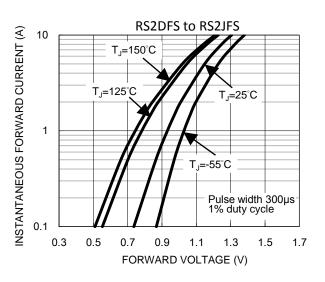
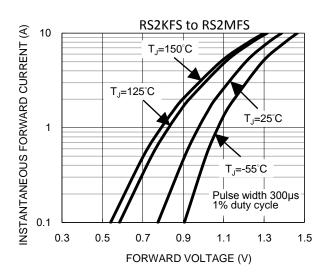


Fig.6 Typical Forward Characteristics





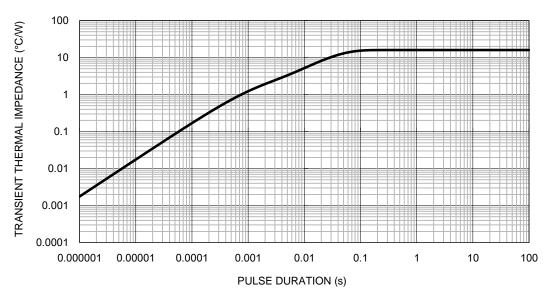
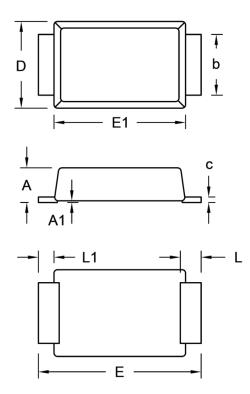


Fig.7 Typical Transient Thermal Impedance

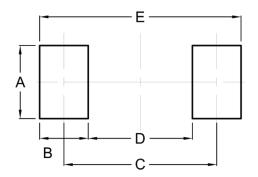
PACKAGE OUTLINE DIMENSIONS

SOD-128



| ым | DIM. | | Unit | inch) | |
|----|------|------|-------|-------|--|
| | Min. | Max. | Min. | Max. | |
| A | 0.90 | 1.10 | 0.035 | 0.043 | |
| A1 | 0.00 | 0.10 | 0.000 | 0.004 | |
| b | 1.60 | 1.90 | 0.063 | 0.075 | |
| с | 0.10 | 0.22 | 0.004 | 0.009 | |
| D | 2.30 | 2.70 | 0.091 | 0.106 | |
| E | 4.40 | 5.00 | 0.173 | 0.197 | |
| E1 | 3.60 | 4.00 | 0.142 | 0.157 | |
| L | 0.40 | 0.80 | 0.016 | 0.031 | |
| L1 | 0.30 | 0.60 | 0.012 | 0.024 | |

SUGGESTED PAD LAYOUT



| Symbol | Unit (mm) | Unit (inch) |
|--------|-----------|-------------|
| A | 2.10 | 0.083 |
| В | 1.40 | 0.055 |
| С | 4.40 | 0.173 |
| D | 3.00 | 0.118 |
| E | 5.80 | 0.228 |

MARKING DIAGRAM



| P/N | = Marking Code |
|-----|----------------|
| YW | = Date Code |
| F | = Factory Code |



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